

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_b
500V	28Ω@10V	0.2A

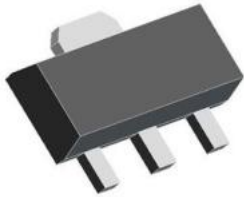
Feature

- Trench Power MV MOSFET Technology
- Excellent Package For Heat Dissipation

Application

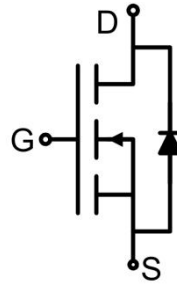
- Load Switch For Portable Devices
- Voltage Controlled Small Signal Switch

Package

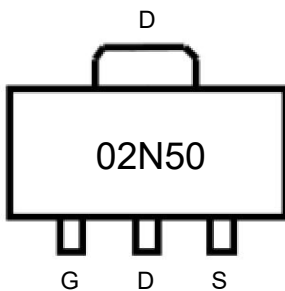


SOT-89

Circuit diagram



Marking



Absolute maximum ratings (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	500	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current ¹⁾	I _D	0.2	A
Pulsed Drain Current ²⁾	I _{DM}	0.8	A
Power Dissipation ¹⁾	P _D	1.56	W
Thermal Resistance from Junction to Ambient ¹⁾	R _{θJA}	83	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	500			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 500V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	3.0	4.0	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 0.1A		22	28	Ω
Dynamic characteristics³⁾						
Input Capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 10V, f = 0.1MHz		51		pF
Output Capacitance	C _{oss}			6.3		
Reverse Transfer Capacitance	C _{rss}			4.6		
Total Gate Charge	Q _g	V _{DS} = 450V, V _{GS} = 10V, I _D = 0.1A		2.2		nC
Gate-Source Charge	Q _{gs}			0.2		
Gate-Drain Charge	Q _{gd}			0.6		
Turn-on delay time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 300V, R _G = 25Ω, I _D = 0.1A		33		nS
Turn-on rise time	t _r			51		
Turn-off delay time	t _{d(off)}			46		
Turn-off fall time	t _f			43		
Source-Drain Diode characteristics						
Diode Forward Current	I _S				0.2	A
Diode Forward voltage	V _{SD}	V _{GS} = 0V, I _S = 0.1A			1.2	V
Reverse Recovery Time	t _{rr}	I _S = 0.2A, di/dt = 100A/μs		98		nS
Reverse Recovery Charge	Q _{rr}				255	

Notes:

- 1) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- 2) Repetitive rating 25mm x 25mm FR4 PCB, D=0.02, pulse width 300μs - pulse width limited by maximum junction temperature.
- 3) Guaranteed by design, not subject to production testing.

Typical Characteristics

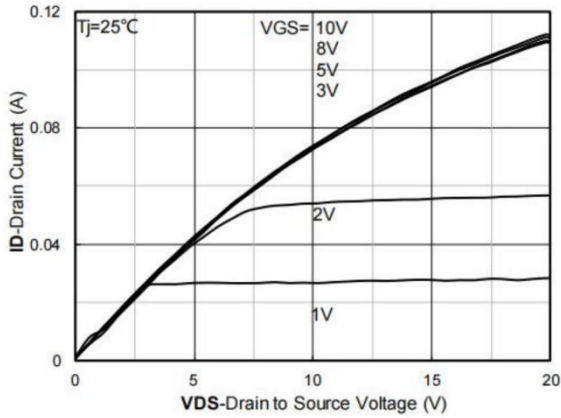


Figure 1. Output Characteristics

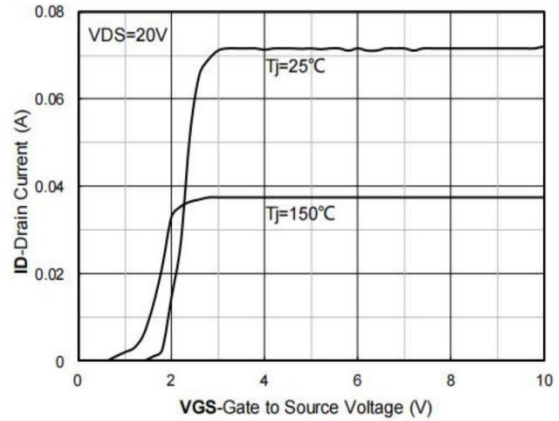


Figure 2. Transfer Characteristics

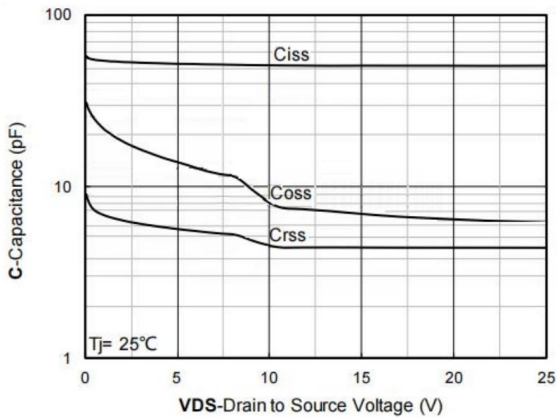


Figure 3. Capacitance Characteristics

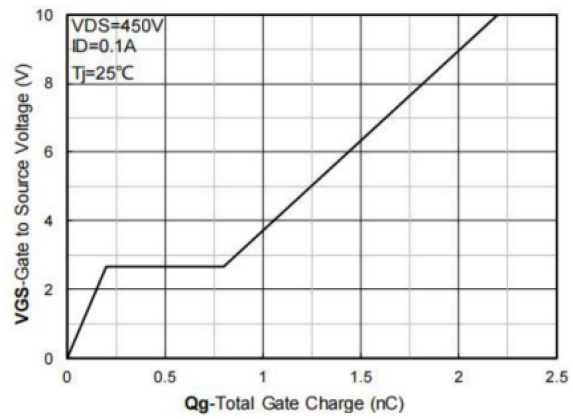


Figure 4. Gate Charge

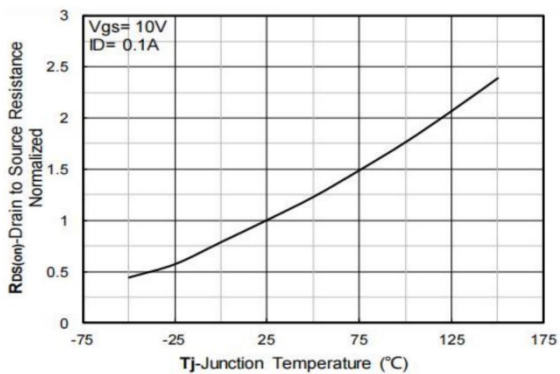


Figure 5. Normalized On-Resistance

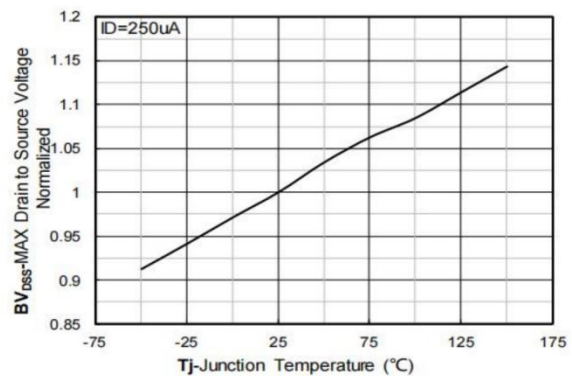
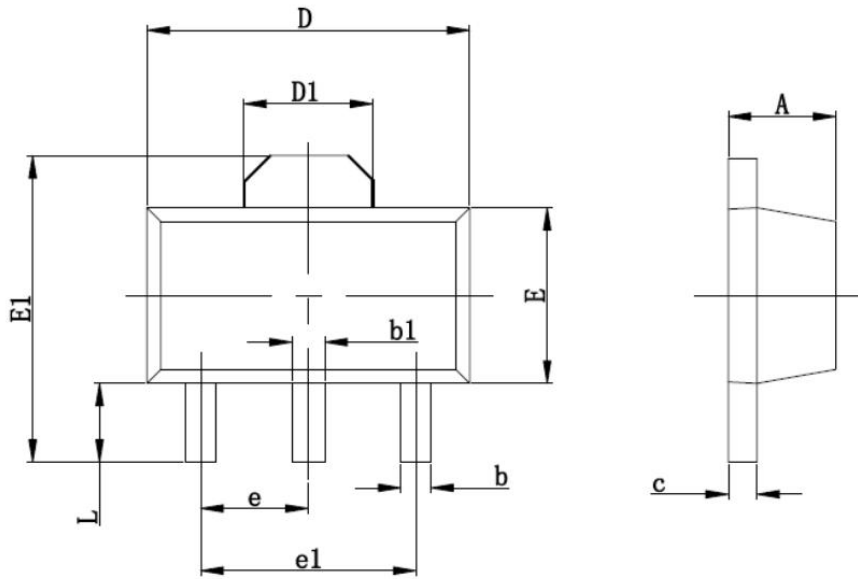


Figure 6. Normalized breakdown voltage

SOT-89 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.300	4.700	0.169	0.185
D1	1.700 REF.		0.067 REF.	
E	2.250	2.650	0.089	0.104
E1	3.910	4.350	0.154	0.171
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.800	1.200	0.031	0.047